

Features

- Frequency Range = 240–930 MHz \blacksquare Antenna diversity and TR switch
- Sensitivity = -118 dBm

SILICON LABS

- +20 dBm Max Output Power
- Configurable $+11$ to $+20$ dBm
- Low Power Consumption
	- \bullet 18.5 mA receive
- \bullet 27 mA $@$ +11 dBm transmit
- \blacksquare Data Rate = 1 to 128 kbps
- \blacksquare Power Supply = 1.8 to 3.6 V
- Ultra low power shutdown mode
- **Digital RSSI**
- Wake-on-radio
- Auto-frequency calibration (AFC)
- control
- Configurable packet structure
- Preamble detector
- TX and RX 64 byte FIFOs
- Low battery detector
- Temperature sensor and 8-bit ADC
- \blacksquare -40 to +85 °C temperature range
- \blacksquare Integrated voltage regulators
- \blacksquare Frequency hopping capability
-
- 20-Pin QFN package

■ Power-on-reset (POR)

- FSK, GFSK, and OOK modulation
- **E** Low BOM

- **Applications**
- Remote control
- Home security & alarm
- **n** Telemetry
- Personal data logging
- Toy control
- Tire Pressure monitoring
- Wireless PC peripherals

Description

Silicon Laboratories' Si4432 highly integrated, single chip wireless ISM transceiver is part of the EZRadioPRO[™] family. The EZRadioPRO family includes a complete line of transmitters, receivers, and transceivers allowing the RF system designer to choose the optimal wireless part for their application.

The Si4432 offers advanced radio features including continuous frequency coverage from 240-930 MHz and adjustable output power of up to +20 dBm. The Si4432ís high level of integration offers reduced BOM cost while simplifying the overall system design. The extremely low receive sensitivity (-118 dBm) coupled with industry leading +20 dBm output power ensures extended range and improved link performance. Built-in antenna diversity and support for frequency hopping can be used to further extend range and enhance performance.

Additional system features such as an automatic wake-up timer, low battery detector, 64 byte TX/RX FIFOs, automatic packet handling, and preamble detection reduce overall current consumption and allow the use of lower-cost system MCUs. An integrated temperature sensor, general purpose ADC, poweron-reset (POR), and GPIOs further reduce overall system cost and size.

The Si4432ís digital receive architecture features a high-performance ADC and DSP based modem which performs demodulation, filtering, and packet handling for increased flexibility and performance. This digital architecture simplifies system design while allowing for the use of lower-end MCUs. The direct digital transmit modulation and automatic PA power ramping ensure precise transmit modulation and reduced spectral spreading ensuring compliance with FCC and ETSI regulations.

Preliminary Rev. 0.4 6/09 Copyright © 2009 by Silicon Laboratories Si4432

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-
- Remote meter reading
- Remote keyless entry
- Home automation
- Industrial control
- \blacksquare Sensor networks
- H Health monitors
- Tag readers

Ordering Information:

See page 156.

Patents pending

\blacksquare On-chip crystal tuning

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1. All specification guaranteed by production test unless otherwise noted.

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Power Amplifier may be damaged if switched on without proper load or termination connected.

1.1. Definition of Test Conditions

Production Test Conditions: T_A = +25 °C

 V_{DD} = +3.3 VDC

External reference signal (XOUT) = 1.0 V_{PP} at 30 MHz, centered around 0.8 VDC

Production test schematic (unless noted otherwise)

All RF input and output levels referred to the pins of the Si4432 (not the RF module)

Extreme Test Conditions:

 $T_A = -40$ to +85 °C V_{DD} = +1.8 to +3.6 VDC External reference signal (XOUT) = 0.7 to 1.6 V_{PP} at 30 MHz centered around 0.8 VDC Production test schematic (unless noted otherwise) All RF input and output levels referred to the pins of the Si4432 (not the RF module)

Test Notes:

All electrical parameters with Min/Max values are guaranteed by one (or more) of the following test methods. Electrical parameters shown with only Typical values are not guaranteed.

- Guaranteed by design and/or simulation but not tested.
- Guaranteed by Engineering Qualification testing at Extreme Test Conditions.
- Guaranteed by 100% Production Test Screening at Production Test Conditions.

2. Functional Description

The Si4432 is a 100% CMOS ISM wireless transceiver with continuous frequency tuning over the complete 240–930 MHz band. The wide operating voltage range of $1.8-3.6$ V and low current consumption makes the Si4432 and ideal solution for battery powered applications.

The Si4432 operates as a time division duplexing (TDD) transceiver where the device alternately transmits and receives data packets. The device uses a singleconversion, image-reject mixer to downconvert the 2 level FSK/GFSK/OOK modulated receive signal to a low IF frequency. Following a programmable gain amplifier (PGA) the signal is converted to the digital domain by a high performance $\Delta \Sigma$ ADC allowing filtering, demodulation, slicing, error correction, and packet handling to be performed in the built-in DSP increasing the receiver's performance and flexibility versus analog based architectures. The demodulated signal is then output to the system MCU through a programmable GPIO or via the standard SPI bus by reading the 64 byte RX FIFO.

A single high precision local oscillator (LO) is used for both transmit and receive modes since the transmitter and receiver do not operate at the same time. The LO is generated by an integrated VCO and $\Delta\Sigma$ Fractional-N PLL synthesizer. The synthesizer is designed to support configurable data rates, output frequency, frequency deviation, and Gaussian filtering at any frequency between 240-930 MHz. The transmit FSK data is modulated directly into the $\Delta \Sigma$ data stream and can be shaped by a Gaussian low-pass filter to reduce unwanted spectral content.

The PA output power can be configured between +11 and +20 dBm in 3 dB steps. The PA is single-ended to allow for easy antenna matching and low BOM cost. The PA incorporates automatic ramp-up and rampdown control to reduce unwanted spectral spreading. The Si4432 supports frequency hopping, TX/RX switch control, and antenna diversity switch control to extend the link range and improve performance. Antenna diversity is completely integrated into the Si4432 and can improve the system link budget by $8-10$ dB, resulting in substantial range increases depending on the environmental conditions. The +20 dBm power amplifier can also be used to compensate for the reduced performance of a lower cost antenna or antenna with size constraints due to a small form-factor. Competing solutions require large and expensive external PAs to achieve comparable performance.

The Si4432 is designed to work with a microcontroller, crystal, and a few passives to create a very low cost system as shown Figure 1. Voltage regulators are integrated on-chip which allow for a wide range of operating supply voltage conditions from +1.8 to +3.6 V. A standard 4-pin SPI bus is used to communicate with the microcontroller. Three configurable general purpose I/Os are available for use to tailor towards the needs of the system. A more complete list of the available GPIO functions is shown in "8. Auxiliary Functions" on page 55 but just to name a few, microcontroller clock output, Antenna Diversity, TRSW control, POR, and specific interrupts. A limited number of passive components are needed to match the LNA and PA. Refer to Figure 32, "Split RF I/Os with Separated TX and RX Connectors-Schematic," on page 70 for the required component values at different frequency ranges.

The application shown in Figure 1 is designed for a system with Antenna Diversity. The Antenna Diversity Control Algorithm is completely integrated into the chip and is discussed further in "Figure 30. GPIO Usage Examples" on page 67.

For a simpler application example not using Antenna Diversity see Figure 32, "Split RF I/Os with Separated TX and RX Connectors-Schematic," on page 70.

R1, L1-L5 and C1-C4 values depend on frequency band, antenna impedance, output power, and supply voltage range. Programmable load capacitors for X1 are integrated.

Figure 1. +20 dBm Application with Antenna Diversity and FHSS

2.1. Operating Modes

The Si4432 provides several modes of operation which can be used to optimize the power consumption of the device application. Depending upon the system communication protocol, the optimal trade-off between the radio wake time and power consumption can be achieved.

Table 9 summarizes the modes of operation of the Si4432. In general, any given mode of operation may be classified as an Active mode or a Power Saving mode. The table indicates which block(s) are enabled (active) in each corresponding mode. With the exception the Shutdown mode, all can be dynamically selected by sending the appropriate commands over the SPI in order to optimize the average current consumption. An X^* in any cell means that, in the given mode of operation, that block can be independently programmed to be either ON or OFF, without noticeably affecting the current consumption. The SPI circuit block includes the SPI interface and the register space. The 32 kHz OSC circuit block includes the 32.768 kHz RC oscillator or 32.768 kHz crystal oscillator, and wake-up timer. AUX (Auxiliary Blocks) includes the temperature sensor, general purpose ADC, and low-battery detector.

Table 9. Operating Modes

3. Controller Interface

3.1. Serial Peripheral Interface (SPI)

The Si4432 communicates with the host MCU over a 3 wire SPI interface: SCLK, SDI, and nSEL. The host MCU can also read data from internal registers on the SDO output pin. A SPI transaction is a 16-bit sequence which consists of a Read-Write (R/W) select bit, followed by a 7-bit address field (ADDR), and an 8-bit data field (DATA), as demonstrated in Figure 2. The 7-bit address field supports reading from or writing to one of the 128, 8-bit control registers. The \overline{R}/W select bit determines whether the SPI transaction is a write or read transaction. If $\overline{R}/W = 1$, it signifies a WRITE transaction, while $\overline{R}/W = 0$ signifies a READ transaction. The contents (ADDR or DATA) are latched into the Si4432 every eight clock cycles. The timing parameters for the SPI interface are shown in Table 10. The SCLK rate is flexible with a maximum rate of 10 MHz.

Figure 2. SPI Timing

Symbol	Parameter	Min (nsec)	Diagram	
t_{CH}	Clock high time	40		
t_{CL}	Clock low time	40	SCLK	
t_{DS}	Data setup time	20	$t_{\rm SS}$ t_{CL} t_{CH} $ t_{DS} t_{DH} $ too t_{SH} t _{DE}	
t_{DH}	Data hold time	20		
t_{DD}	Output data delay time	20	SDI	
t_{EN}	Output enable time	20	SDO t_{EN}	
t_{DE}	Output disable time	50	t_{SW}	
t_{SS}	Select setup time	20	nSEL	
t_{SH}	Select hold time	50		
t_{SW}	Select high period	80		

Table 10. Serial Interface Timing Parameters

To read back data from the Si4432, the \overline{R}/W bit must be set to 0 followed by the 7-bit address of the register from which to read. The 8 bit DATA field following the 7-bit ADDR field is ignored when R/W = 0. The next eight negative edge transitions of the SCLK signal will clock out the contents of the selected register. The data read from the selected register will be available on the SDO output pin. The READ function is shown in Figure 3. After the READ function is completed the SDO pin will remain at either a logic 1 or logic 0 state depending on the last data bit clocked out (D0). When nSEL goes high the SDO output pin will be pulled high by internal pullup.

The SPI interface contains a burst read/write mode which will allows for reading/writing sequential registers without having to re-send the SPI address. When the nSEL bit is held low while continuing to send SCLK pulses, the SPI interface will automatically increment the ADDR and read from/write to the next address. An SPI burst write transaction is demonstrated in Figure 4 and burst read in Figure 3. As long as nSEL is held low, input data will be latched into the Si4432 every eight SCLK cycles. A burst read transaction is also demonstrated in Figure 5.

3.2. Operating Mode Control

There are four primary states in the Si4432 radio state machine: SHUTDOWN, IDLE, TX, and RX (see Figure 6). The SHUTDOWN state completely shuts down the radio to minimize current consumption. There are five different configurations/options for the IDLE state which can be selected to optimize the chip to the applications needs. "Register 07h. Operating Mode and Function Control 1" controls which operating mode/state is selected. The TX and RX state may be reached automatically from any of the IDLE states by setting the txon/rxon bits in "Register 07h. Operating Mode and Function Control 1". Table 11 shows each of the operating modes with the time required to reach either RX or TX mode as well as the current consumption of each mode.

The output of the LPLDO is internally connected in parallel to the output of the main digital regulator (and is available externally at the VR_DIG pin); this common digital supply voltage is connected to all digital circuit blocks, including the digital modem, crystal oscillator, and SPI and register space. The LPLDO has extremely low quiescent current consumption but limited current supply capability; it is used only in the IDLE-STANDBY and IDLE-SLEEP modes.

Figure 6. State Machine Diagram

Table 11. Operating Modes

3.2.1. Shutdown State

The shutdown state is the lowest current consumption state of the device with nominally less than 10 nA of current consumption. The shutdown state may be entered by driving the SDN pin (Pin 20) high. The SDN pin should be held low in all states except the SHUTDOWN state. In the SHUTDOWN state, the contents of the registers are lost and there is no SPI access.

When the chip is connected to the power supply, a POR will be initiated after the falling edge of SDN.

3.2.2. Idle State

There are five different modes in the IDLE state which may be selected by "Register 07h. Operating Mode and Function Control 1". All modes have a tradeoff between current consumption and response time to TX/RX mode. This tradeoff is shown in Table 11. After the POR event, SWRESET, or exiting from the SHUTDOWN state the chip will default to the IDLE-READY mode. After a POR event the interrupt registers must be read to properly enter the SLEEP, SENSOR, or STANDBY mode and to control the 32 kHz clock correctly.

3.2.2.1. STANDBY Mode

STANDBY mode has the lowest current consumption possible with only the LPLDO enabled to maintain the register values. In this mode the registers can be accessed in both read and write mode. The standby mode can be entered by writing 0h to "Register 07h. Operating Mode and Function Control 1". If an interrupt has occurred (i.e., the nIRQ pin = 0) the interrupt registers must be read to achieve the minimum current consumption. Additionally, the ADC should not be selected as an input to the GPIO in this mode as it will cause excess current consumption.

3.2.2.2. SLEEP Mode

In SLEEP mode the LPLDO is enabled along with the Wake-Up-Timer, which can be used to accurately wake-up the radio at specified intervals. See "8.6. Wake-Up Timer" on page 63 for more information on the Wake-Up-Timer. Sleep mode is entered by setting enwt = 1 (40h) in "Register 07h. Operating Mode and Function Control 1". If an interrupt has occurred (i.e., the nIRQ pin = 0) the interrupt registers must be read to achieve the minimum current consumption. Also, the ADC should not be selected as an input to the GPIO in this mode as it will cause excess current consumption.

3.2.2.3. SENSOR Mode

In SENSOR Mode either the Low Battery Detector, Temperature Sensor, or both may be enabled in addition to the LPLDO and Wake-Up-Timer. The Low Battery Detector can be enabled by setting enlbd = 1 and the temperature sensor can be enabled by setting ents = 1 in "Register 07h. Operating Mode and Function Control 1". See "8.4. Temperature Sensor" on page 60 and "8.5. Low Battery Detector" on page 62 for more information on these features. If an interrupt has occurred (i.e., the nIRQ pin = 0) the interrupt registers must be read to achieve the minimum current consumption.

3.2.2.4. READY Mode

READY Mode is designed to give a fast transition time to TX mode with reasonable current consumption. In this mode the Crystal oscillator remains enabled reducing the time required to switch to the TX or RX mode by eliminating the crystal start-up time. Ready mode is entered by setting xton = 1 in "Register 07h. Operating Mode and Function Control 1". To achieve the lowest current consumption state the crystal oscillator buffer should be disabled. This is done by setting "Register 62h. Crystal Oscillator/Power-on-Reset Control" to a value of 02h. To exit ready mode, bufovr (bit 1) of this register must be set back to 0.

3.2.2.5. TUNE Mode

In TUNE Mode the PLL remains enabled in addition to the other blocks enabled in the IDLE modes. This will give the fastest response to TX mode as the PLL will remain locked but it results in the highest current consumption. This mode of operation is designed for Frequency Hopping Systems (FHS). Tune mode is entered by setting pllon = 1 in "Register 07h. Operating Mode and Function Control 1". It is not necessary to set xton to 1 for this mode, the internal state machine automatically enables the crystal oscillator.

3.2.3. TX State

The TX state may be entered from any of the IDLE modes when the txon bit is set to 1 in "Register 07h. Operating Mode and Function Control 1". A built-in sequencer takes care of all the actions required to transition between states from enabling the crystal oscillator to ramping up the PA to prevent unwanted spectral splatter. The following sequence of events will occur automatically when going from STANDBY mode to TX mode by setting the txon bit.

- 1. Enable the Main Digital LDO and the Analog LDOs.
- 2. Start up crystal oscillator and wait until ready (controlled by timer).
- 3. Enable PLL.
- 4. Calibrate VCO (this action is skipped when the vcocal bit is 0 ⁿ, default value is 1 ⁿ).
- 5. Wait until PLL settles to required transmit frequency (controlled by timer).
- 6. Activate Power Amplifier and wait until power ramping is completed (controlled by timer).
- 7. Transmit Packet.

The first few steps may be eliminated depending on which IDLE mode the chip is configured to prior to setting the txon bit. By default, the VCO and PLL are calibrated every time the PLL is enabled. If the ambient temperature is constant and the same frequency band is being used these functions may be skipped by setting the appropriate bits in "Register 55h. Calibration Control".

3.2.4. RX State

The RX state may be entered from any of the Idle modes when the rxon bit is set to 1 in "Register 07h. Operating Mode and Function Control 1". A built-in sequencer takes care of all the actions required to transition from one of the IDLE modes to the RX state. The following sequence of events will occur automatically to get the chip into RX mode when going from STANDBY mode to RX mode by setting the rxon bit:

- 1. Enable the Main Digital LDO and the Analog LDOs.
- 2. Start up crystal oscillator and wait until ready (controlled by timer).
- 3. Enable PLL.
- 4. Calibrate VCO (this action is skipped when the vcocal bit is "0", default value is "1").
- 5. Wait until PLL settles to required transmit frequency (controlled by timer).
- 6. Enable receive circuits: LNA, mixers, and ADC.
- 7. Calibrate ADC (RC calibration).
- 8. Enable receive mode in the digital modem.

Depending on the configuration of the radio all or some of the following functions will be performed automatically by the digital modem: AGC, AFC (optional), update status registers, bit synchronization, packet handling (optional) including sync word, header check, and CRC.

3.2.5. Device Status

The operational status of the chip can be read from "Register 02h. Device Status".

3.3. Interrupts

The Si4432 is capable of generating an interrupt signal when certain events occur. The chip notifies the microcontroller that an interrupt event has been detected by setting the nIRQ output pin LOW = 0. This interrupt signal will be generated when any one (or more) of the interrupt events (corresponding to the Interrupt Status bits) shown below occur. The nIRQ pin will remain low until the microcontroller reads the Interrupt Status Register(s) (Registers 03h-04h) containing the active Interrupt Status bit; the nIRQ output signal will then be reset until the next change in status is detected. All of the interrupts must be enabled by the corresponding enable bit in the Interrupt Enable Registers (Registers 05h-06h). All enabled interrupt bits will be cleared when the microcontroller reads the interrupt status register. If the interrupt is not enabled when the event occurs inside of the chip it will not trigger the nIRQ pin, but the status may still be read correctly at anytime in the Interrupt Status registers.

See "Register 03h. Interrupt/Status 1," on page 89 and "Register 04h. Interrupt/Status 2," on page 91 for a complete list of interrupts.

3.4. Device Code

The device version code is readable from "Register 01h. Version Code (VC)". This is a read only register.

3.5. System Timing

The system timing for TX and RX modes is shown in Figures 8 and 7. The timing is shown transitioning from STANDBY mode to TX mode and going automatically through the built-in sequencer of required steps. If a small range of frequencies is being used and the temperature range is fairly constant a calibration may only be needed at the initial power up of the device. The relevant system timing registers are shown below.

The VCO will automatically calibrate at every frequency change or power up. The VCO CAL may also be forced by setting the vcocal bit. The 32.768 kHz RC oscillator is also automatically calibrated but the calibration may also be forced. The enrcfcal will enable the RC Fine Calibration which will occur every 30 seconds. The rccal bit will force a complete calibration of the RC oscillator which will take approximately 2 ms. The PLL T0 time is to allow for bias settling of the VCO, the default for this should be adequate. The PLL TS time is for the settling time of the PLL, which has a default setting of 200 µs. This setting should be adequate for most applications but may be reduced if small frequency jumps are used. For more information on the PLL register configuration options, see "Register 53h. PLL Tune Time," on page 133 and "Register 55h. Calibration Control," on page 134.

3.6. Frequency Control

For calculating the necessary frequency register settings it is recommended that customers use the easy control window in Silicon Labs' Wireless Design Suite (WDS) or the Excel Calculator available on the product website. These methods offer a simple method to quickly determine the correct settings based on the application requirements. The following information can be used to calculated these values manually.

3.6.1. Frequency Programming

In order to receive or transmit an RF signal, the desired channel frequency, fcarrier, must be programmed into the Si4432. Note that this frequency is the center frequency of the desired channel and not an LO frequency. The carrier frequency is generated by a Fractional-N Synthesizer, using 10 MHz both as the reference frequency and the clock of the (3rd order) $\Delta\Sigma$ modulator. This modulator uses modulo 64000 accumulators. This design was made to obtain the desired frequency resolution of the synthesizer. The overall division ratio of the feedback loop consist of an integer part (N) and a fractional part (F).In a generic sense, the output frequency of the synthesizer is:

$$
f_{OUT}=10MHz\times(N+F)
$$

The fractional part (F) is determined by three different values, Carrier Frequency (fc[15:0]), Frequency Offset (fo[8:0]), and Frequency Modulation (fd[7:0]). Due to the fine resolution and high loop bandwidth of the synthesizer, FSK modulation is applied inside the loop and is done by varying F according to the incoming data; this is discussed further in "3.6.4. Frequency Deviation" on page 29. Also, a fixed offset can be added to fine-tune the carrier frequency and counteract crystal tolerance errors. For simplicity assume that only the fc[15:0] register will determine the fractional component. The equation for selection of the carrier frequency is shown below:

$$
f_{\text{carrier}} = 10MHz \times (hbsel + 1) \times (N + F)
$$

$$
f_{\text{TX}} = 10MHz^* (hbsel + 1) * (fb[4:0] + 24 + \frac{fc[15:0]}{64000})
$$

The integer part (N) is determined by fb[4:0]. Additionally, the output frequency can be halved by connecting a $\div 2$ divider to the output. This divider is not inside the loop and is controlled by the hbsel bit in "Register 75h. Frequency Band Select". This effectively partitions the entire 240–930 MHz frequency range into two separate bands: High Band (HB) for hbsel = 1, and Low Band (LB) for hbsel = 0. The valid range of fb[4:0] is from 0 to 23. If a higher value is written into the register, it will default to a value of 23. The integer part has a fixed offset of 24 added to it as shown in the formula above. Table 12 demonstrates the selection of fb[4:0] for the corresponding frequency band.

After selection of the fb (N) the fractional component may be solved with the following equation:

$$
fc[15:0] = \left(\frac{f_{TX}}{10MHz*(hbsel+1)} - fb[4:0] - 24\right) * 64000
$$

fb and fc are the actual numbers stored in the corresponding registers.

fb[4:0] Value	N	Frequency Band		
		hbsel=0	$hbsel=1$	
0	24	240-249.9 MHz	480-499.9 MHz	
1	25	250-259.9 MHz	500-519.9 MHz	
$\overline{2}$	26	260-269.9 MHz	520-539.9 MHz	
3	27	270-279.9 MHz	540-559.9 MHz	
4	28	280-289.9 MHz	560-579.9 MHz	
5	29	290-299.9 MHz	580-599.9 MHz	
6	30	300-309.9 MHz	600-619.9 MHz	
7	31	310-319.9 MHz	620-639.9 MHz	
8	32	320-329.9 MHz	640-659.9 MHz	
9	33	330-339.9 MHz	660-679.9 MHz	
10	34	340-349.9 MHz	680-699.9 MHz	
11	35	350-359.9 MHz	700-719.9 MHz	
12	36	360-369.9 MHz	720-739.9 MHz	
13	37	370-379.9 MHz	740-759.9 MHz	
14	38	380-389.9 MHz	760-779.9 MHz	
15	39	390-399.9 MHz	780-799.9 MHz	
16	40	400-409.9 MHz	800-819.9 MHz	
17	41	410-419.9 MHz	820-839.9 MHz	
18	42	420-429.9 MHz	840-859.9 MHz	
19	43	430-439.9 MHz	860-879.9 MHz	
20	44	440-449.9 MHz	880-899.9 MHz	
21	45	450-459.9 MHz	900-919.9 MHz	
22	46	460-469.9 MHz	920-930.0 MHz	
23	47	470-479.9 MHz		

Table 12. Frequency Band Selection

The chip will automatically shift the frequency of the Synthesizer down by 937.5 kHz (30 MHz \div 32) to achieve the correct Intermediate Frequency (IF) when RX mode is entered. Low-side injection is used in the RX Mixing architecture; therefore, no frequency reprogramming is required when using the same TX frequency and switching between RX/TX modes.

3.6.2. Easy Frequency Programming for FHSS

While Registers 73h–77h may be used to program the carrier frequency of the Si4432, it is often easier to think in terms of "channels" or "channel numbers" rather than an absolute frequency value in Hz. Also, there may be some timing-critical applications (such as for Frequency Hopping Systems) in which it is desirable to change frequency by programming a single register. Once the channel step size is set, the frequency may be changed by a single register corresponding to the channel number. A nominal frequency is first set using Registers 73h–77h, as described above. Registers 79h and 7Ah are then used to set a channel step size and channel number, relative to the nominal setting. The Frequency Hopping Step Size (fhs[7:0]) is set in increments of 10 kHz with a maximum channel step size of 2.56 MHz. The Frequency Hopping Channel Select Register then selects channels based on multiples of the step size.

$F_{\text{carrier}} = \text{From} + \text{fhs}[7:0] \times (\text{fhch}[7:0] \times 10 \text{kHz})$

For example: if the nominal frequency is set to 900 MHz using Registers 73h-77h and the channel step size is set to 1 MHz using "Register 7Ah. Frequency Hopping Step Size". For example, if the "Register 79h. Frequency Hopping Channel Select" is set to 5d, the resulting carrier frequency would be 905 MHz. Once the nominal frequency and channel step size are programmed in the registers, it is only necessary to program the fhch[7:0] register in order to change the frequency.

3.6.3. Automatic Frequency Change

If registers 79h or 7Ah are changed in either TX or mode, the state machine will automatically transition the chip back to tune, change the frequency, and automatically go back to either TX or RX. This feature is useful to reduce the number of SPI commands required in a Frequency Hopping System. This in turn reduces microcontroller activity, reducing current consumption.

3.6.4. Frequency Deviation

The peak frequency deviation is configurable from ± 1 to ± 320 kHz. The Frequency Deviation (Δf) is controlled by the Frequency Deviation Register (fd), address 71 and 72h, and is independent of the carrier frequency setting. When enabled, regardless of the setting of the hbsel bit (high band or low band), the resolution of the frequency deviation will remain in increments of 625 Hz. When using frequency modulation the carrier frequency will deviate from the nominal center channel carrier frequency by $\pm \Delta f$:

$$
\Delta f = fd[8:0] \times 625Hz
$$

$$
fd[8:0] = \frac{\Delta f}{625Hz} \quad \Delta f = \text{peak deviation}
$$

Figure 9. Frequency Deviation

The previous equation should be used to calculate the desired frequency deviation. If desired, frequency modulation may also be disabled in order to obtain an unmodulated carrier signal at the channel center frequency; see "4.1. Modulation Type" on page 34 for further details.

3.6.5. Frequency Offset Adjustment

When the AFC is disabled the frequency offset can be adjusted manually by fo[9:0] in registers 73h and 74h. The frequency offset adjustment and the AFC both are implemented by shifting the Synthesizer Local Oscillator frequency. This register is a signed register so in order to get a negative offset you will need to take the twos complement of the positive offset number. The offset can be calculated by the following:

 $DesiredOffset = 156.25Hz \times (hbsel + 1) \times f0[9:0]$

 $156.25Hz \times (hbsel + 1)$ $[9:0]$ $\times (hbsel +$ $=$ *Hz hbsel* $f_0[9:0] = \frac{DesiredOffice}{\sqrt{15.05556}}$

The adjustment range in high band is: ±160 kHz, and adjustment range in low band is: ±80 kHz. For example to compute an offset of +50 kHz in high band mode fo[9:0] should be set to 0A0h. For an offset of -50 kHz in high band mode the fo[9:0] register should be set to 360h.

When AFC is enabled the same registers can be used to read the offset value as automatically obtained by the AFC. A stable offset value can read after preamble detection using the preamble detection or sync word detection interrupt.

3.6.6. Auto Frequency Control (AFC)

The receiver supports automatic frequency control (AFC) to compensate for frequency differences between the transmitter and receiver reference frequencies. These differences can be caused by the absolute accuracy and temperature dependencies of the reference crystals. Due to frequency offset compensation in the modem, the receiver is tolerant to frequency offsets up to 0.25 times the IF bandwidth when the AFC is disabled. When the AFC is enabled, the received signal will be centered in the pass-band of the IF filter, providing optimal sensitivity and selectivity over a wider range of frequency offsets up to 0.35 times the IF bandwidth. The trade-off of receiver sensitivity (at 1% PER) versus carrier offset and the impact of AFC are illustrated in Figure 10.

Figure 10. Sensitivity at 1% PER vs. Carrier Frequency Offset

The AFC function shares registers 73h and 74h with the Frequency Offset setting. If AFC is enabled (D6 in "Register 1Dh. AFC Loop Gearshift Override," on page 109), the Frequency Offset shows the results of the AFC algorithm for the current receive slot. When selecting the preamble length, the length needs to be long enough to settle the AFC. In general two bytes of preamble is sufficient to settle the AFC. Disabling the AFC allows the preamble to be shortened by about 8 bits. Note that with the AFC disabled, the preamble length must still be long enough to settle the receiver and to detect the preamble (see "6.7. Preamble Length" on page 47). The AFC corrects the detected frequency offset by changing the frequency of the Fractional-N PLL. When the preamble is detected, the AFC will freeze. In multi-packet mode the AFC is reset at the end of every packet and will re-acquire the frequency offset for the next packet. An automatic reset circuit prevents excessive drift by resetting the AFC loop when the tuning exceeds 2 times the frequency deviation (as set by fd[8:0] in register 71h and 72h) in high band or 1 times the frequency deviation in low band. This range can be halved by the "afcbd" bit in register 1Dh. If needed, fd[8:0] can have a different value in RX mode compared to TX mode.

In TX mode, the "Register 73h. Frequency Offset 1" is used to provide an offset to the programmed transmit frequency. This offset allows fine tuning of the transmit frequency to account for the variability of the TX reference frequency. Note that reading this register shows the frequency offset calculated from the last AFC action, not what was previously written to the Frequency Offset register.

The amount of feedback to the Fractional-N PLL before the preamble is detected is controlled from afcgearh[2:0]. The default value 000 relates to a feedback of 100% from the measured frequency error and is advised for most applications. Every bit added will half the feedback but will require a longer preamble to settle. The amount of feedback after the preamble is detected is controlled from afcgearl[2:0].

The AFC operates as follows. The frequency error of the incoming signal is measured over a period of two bit times, after which it corrects the local oscillator via the Fractional-N PLL. After this correction, some time is allowed to settle the Fractional-N PLL to the new frequency before the next frequency error is measured. The duration of the AFC cycle before the preamble is detected can be programmed with shwait[2:0] ("Register 1Eh. AFC Timing Control,î on page 110). It is advised to use the default value 001, which sets the AFC cycle to 4 bit times (2 for measurement and 2 for settling). The duration of the AFC cycle after the preamble detection and before the end of the preamble can be programmed with lgwait[2:0]. It is advised to use the default value 000 such that the AFC is disabled after the preamble is detected.

3.6.7. TX Data Rate Generator

The data rate is configurable between 1-128 kbps. For data rates below 30 kbps the "txdtrtscale" bit in register 70h should be set to 1. When higher data rates are used this bit should be set to 0**.**

The TX date rate is determined by the following formula:

$$
DR_TX = \frac{txdr[15:0] \times 1MHz}{2^{16+5 \cdot txdtrtscale}}
$$

$$
txdr[15:0] = \frac{DR_TX \times 2^{16+5 \cdot txdrrscale}}{1MHz}
$$

The txdr register may be found in the following registers.

4. Modulation Options

4.1. Modulation Type

The Si4432 supports three different modulation options: Gaussian Frequency Shift Keying (GFSK), Frequency Shift Keying (FSK), and On-Off Keying (OOK). GFSK is the recommended modulation type as it provides the best performance and cleanest modulation spectrum. Figure 11 demonstrates the difference between FSK and GFSK for a Data Rate of 64 kbps. The time domain plots demonstrate the effects of the Gaussian filtering. The frequency domain plots demonstrate the spectral benefit of GFSK over FSK. The type of modulation is selected with the modtyp[1:0] bits in "Register 71h. Modulation Mode Control 2". Note that it is also possible to obtain an unmodulated carrier signal by setting modtyp[1:0] = 00.

Figure 11. FSK vs GFSK Spectrums

4.2. Modulation Data Source

The Si4432 may be configured to obtain its modulation data from one of three different sources: FIFO mode, Direct Mode, and from a PN9 mode. Furthermore, in Direct Mode, the TX modulation data may be obtained from several different input pins. These options are set through the dtmod[1:0] field in "Register 71h. Modulation Mode Control 2".

4.3. FIFO Mode

In FIFO mode, the integrated FIFOs are used to transmit and receive the data. The FIFOs are accessed via "Register 7Fh. FIFO Access" with burst read/write capability. The FIFOs may be configured specific to the application packet size, etc. (see "6. Data Handling and Packet Handler" on page 42 for further information).

When in FIFO mode the chip will automatically exit the TX or RX State when either the *ipksent* or *ipkvalid* interrupt occurs. The chip will return to any of the other states based on the settings in "Register 07h. Operating Mode and Function Control 1". For instance, if the chip is put into TX mode and both the txon and pllon bits are set, the chip will transmit all of the contents of the FIFO and the ipksent interrupt will occur. When this event occurs the chip will clear the txon bit and return to pllon or Tune Mode. If no other bits are set in register 07h besides txon initially then the chip will return to the Idle state.

In RX mode the rxon bit will only be cleared if ipkvalid occurs. A CRC, Header, or Sync error will generate an interrupt and the microcontroller will need to decide on the next action.

4.4. Direct Mode

For legacy systems that have packet handling within an MCU or other baseband chip, it may not be desirable to use the FIFO. For this scenario, a Direct Mode is provided which bypasses the FIFOs entirely. In Direct Mode, the TX modulation data is applied to an input pin of the chip and processed in "real time" (i.e., not stored in a register for transmission at a later time). There are various configurations for choosing which pin is used for the TX Data. Furthermore, an additional input pin is required for the TX Data Clock if GFSK modulation is desired (only the TX Data input pin is required for FSK). Two options for the source of the TX Data are available in the dtmod[1:0] field, and various configurations for the source of the TX Data Clock may be selected through the trclk[1:0] field.

The eninv bit in Address 71h will invert the TX Data for testing purposes.

4.5. PN9 Mode

In this mode the TX Data is generated internally using a pseudorandom (PN9 sequence) bit generator. The primary purpose of this mode is for use as a test mode to observe the modulated spectrum without having to load/provide data.

4.6. Synchronous vs. Asynchronous

In Asynchronous mode no clock is used to synchronize the data to the internal modulator. This mode can only be used with FSK. The advantage of this mode that it saves a microcontroller pin because no data clock is required. The disadvantage is that you donít get the clean spectrum and limited BW of GFSK. If Asynchronous FSK is used the TX DR register should be set to its maximum value.

Figure 12. Direct Synchronous Mode Example

Figure 13. Direct Asynchronous Mode Example

Figure 14. FIFO Mode Example

5. Internal Functional Blocks

This section provides an overview some of the key blocks of the internal radio architecture.

5.1. RX LNA

The input frequency range for the LNA is 240–930 MHz. The LNA provides gain with a noise figure low enough to suppress the noise of the following stages. The LNA has one step of gain control which is controlled by the analog gain control (AGC) algorithm. The AGC algorithm adjusts the gain of the LNA and PGA so the receiver can handle signal levels from sensitivity to +5 dBm with optimal performance.

5.2. RX I-Q Mixer

The output of the LNA is fed internally to the input of the receive mixer. The receive mixer is implemented as an I-Q mixer that provides both I and Q channel outputs to the programmable gain amplifier. The mixer consists of two double-balanced mixers whose RF inputs are driven in parallel, local oscillator (LO) inputs are driven in quadrature, and separate I and Q Intermediate Frequency (IF) outputs drive the programmable gain amplifier. The receive LO signal is supplied by an integrated VCO and PLL synthesizer operating between 240–930 MHz. The necessary quadrature LO signals are derived from the divider at the VCO output.

5.3. Programmable Gain Amplifier

The Programmable Gain Amplifier (PGA) provides the necessary gain to boost the signal level into the Dynamic Range of the ADC. The PGA must also have enough gain switching to allow for large input signals to ensure a linear RSSI range up to -20 dBm. The PGA is designed to have steps of 3 dB which are controlled by the AGC algorithm in the digital modem.

5.4. ADC

The amplified I&Q IF signals are digitized using an Analog-to-Digital Converter (ADC), which allows for low current consumption and high dynamic range. The bandpass response of the ADC provides exceptional rejection of out of band blockers.

5.5. Digital Modem

Using high-performance ADCs allows channel filtering, image rejection, and demodulation to be performed in the digital domain, resulting in reduced area while increasing flexibility. The digital modem performs the following functions:

- Channel Selection Filter
- **TX Modulation**
- RX Demodulation
- AGC
- Preamble Detector
- Invalid Preamble Detector
- Radio Signal Strength Indicator (RSSI)
- Automatic Frequency Compensation (AFC)
- Packet Handling including $EZMacTM$ features
- Cyclic Redundancy Check (CRC)

The digital Channel Filter and Demodulator are optimized for ultra low power consumption and are highly configurable. Supported modulation types are GFSK, FSK, and OOK. The Channel Filter can be configured to support a large choice of bandwidths ranging from 620 kHz down to 2.6 kHz. A large variety of data rates are supported ranging from 1 up to 128 kbps. The AGC algorithm is implemented digitally using an advanced control loop optimized for fast response time.

The configurable Preamble Detector is used to improve the reliability of the Sync-word detection. The Sync-word detector is only enabled when a valid preamble is detected, significantly reducing the probability of false Sync-word detection.

The Invalid Preamble Detector issues an interrupt when no valid preamble signal is found. After the receiver is enabled, the Invalid Preamble Detector output is ignored for 16 Tb (Where Tb is the time of a bit duration) to allow the receiver to settle. The Invalid Preamble Detect interrupt can be used to save power and speed-up search in receive mode. It is advised to mask the invalid preamble interrupt when Antenna Diversity is enabled.

The Received Signal Strength Indicator (RSSI) provides a measure of the signal strength received on the tuned channel. The resolution of the RSSI is 0.5 dB. This high resolution RSSI enables accurate channel power measurements for clear channel assessment (CCA), carrier sense (CS), and listen before talk (LBT) functionality.

Frequency mistuning caused by crystal inaccuracies can be compensated by enabling the digital Automatic Frequency Control (AFC) in receive mode.

A comprehensive programmable Packet Handler including key features of Silicon Labs' EZMacTM is integrated to create a variety of communication topologies ranging from peer-to-peer networks to mesh networks. The extensive programmability of the packet header allows for advanced packet filtering which in turn enables a mix of broadcast, group, and point-to-point communication.

A wireless communication channel can be corrupted by noise and interference, and it is therefore important to know if the received data is free of errors. A cyclic redundancy check (CRC) is used to detect the presence of erroneous bits in each packet. A CRC is computed and appended at the tail of each transmitted packet and verified by the receiver to confirm that no errors have occurred. The Packet Handler and CRC are extremely valuable features which can significantly reduce the load on the system microcontroller allowing for a simpler and cheaper microcontroller.

The digital modem includes the TX Modulator which converts the TX Data bits into the corresponding stream of digital modulation values to be summed with the fractional input to the sigma-delta modulator. This modulation approach results in highly accurate resolution of the frequency deviation. A Gaussian filter is implemented to support GFSK, considerably reducing the energy in the adjacent channels. The bandwidth-time product (BT) is 0.5 for all programmed data rates.

5.6. Synthesizer

An integrated Sigma Delta ($\Sigma\Delta$) Fractional-N PLL synthesizer capable of operating from 240–930 MHz is provided on-chip. Using a $\Sigma\Delta$ synthesizer has many advantages; it provides large amounts of flexibility in choosing data rate, deviation, channel frequency, and channel spacing. The transmit modulation is applied directly to the loop in the digital domain through the fractional divider which results in very precise accuracy and control over the transmit deviation.

The PLL and Δ - Σ modulator scheme is designed to support any desired frequency and channel spacing in the range from 240–930 MHz with a frequency resolution of 156.25 Hz (Low band) or 312.5 Hz (High band). The transmit data rate can be programmed between 1-128 kbps, and the frequency deviation can be programmed between ±1–160 kHz. These parameters may be adjusted via registers as shown in "3.6. Frequency Control" on page 27.

Figure 15. PLL Synthesizer Block Diagram

The reference frequency to the PLL is 10 MHz. The PLL utilizes a differential L-C VCO, with integrated on-chip spiral inductors. The output of the VCO is followed by a configurable divider which will divide down the signal to the desired output frequency band. The modulus of this divider stage is controlled dynamically by the output from the Δ - Σ modulator. The tuning resolution of the Δ - Σ modulator is determined largely by the over-sampling rate and the number of bits carried internally. The tuning resolution is sufficient to tune to the commanded frequency with a maximum accuracy of 312.5 Hz anywhere in the range between 240–930 MHz.

5.6.1. VCO

The output of the VCO is automatically divided down to the correct output frequency depending on the hbsel and fb[4:0] fields in "Register 75h. Frequency Band Select". A 2X VCO is utilized to help avoid problems due to frequency pulling, especially when turning on the integrated Power Amplifier. In receive mode, the LO frequency is automatically shifted downwards (without reprogramming) by the IF frequency of 937.5 kHz, allowing transmit and receive operation on the same frequency. The VCO integrates the resonator inductor, tuning varactor, so no external VCO components are required.

The VCO uses capacitance bank to cover the wide frequency range specified. The capacitance bank will automatically be calibrated every time the synthesizer is enabled. In certain fast hopping applications this might not be desirable so the VCO calibration may be skipped by setting the appropriate register.

5.7. Power Amplifier

The Si4432 contains an internal integrated power amplifier (PA) capable of transmitting at output levels between +11 to +20 dBm. The output power is programmable in 3 dB steps through the txpow[1:0] field in "Register 6Dh. TX Power".

The PA design is single-ended and is implemented as a two stage class CE amplifier with efficiency in the range of 45–50% while transmitting at maximum power. The efficiency drops to approximately 20% when operating at the lowest power steps. Due to the high efficiency a simple filter is required on the board to filter the harmonics. The PA output is ramped up and down to prevent unwanted spectral splatter.

5.7.1. Output Power Selection

The output power is configurable in 3 dB steps from +11 dBm to +20 dBm with the txpow[1:0] field in "Register 6Dh. TX Power". Note that Frequency Hopping (FHSS) is required by the FCC when using an output power level of +20 dBm. The PA output is ramped up and down to prevent unwanted spectral splatter.

The extra output power can allow use of a cheaper smaller antenna, greatly reducing the overall BOM cost. The higher power setting of the chip achieves maximum possible range, but of course comes at the cost of higher TX current consumption. However, depending on the duty cycle of the system, the effect on battery life may be insignificant. Contact Silicon Labs Support for help in evaluating this tradeoff.

5.8. Crystal Oscillator

The Si4432 includes an integrated 30 MHz crystal oscillator with a fast start-up time of less than 600 µs when a suitable parallel resonant crystal is used. The design is differential with the required crystal load capacitance integrated on-chip to minimize the number of external components. By default, all that is required off-chip is the 30 MHz crystal blank.

The crystal load capacitance can be digitally programmed to accommodate crystals with various load capacitance requirements and to slightly adjust the frequency of the crystal oscillator. The tuning of the crystal load capacitance is programmed through the xlc[6:0] field of "Register 09h. 30 MHz Crystal Oscillator Load Capacitance". The total internal capacitance is 12.5 pF and is adjustable in approximately 127 steps (97fF/step). The xtalshift bit is a course shift in frequency but is not binary with xlc[6:0].

The crystal load capacitance can be digitally programmed to accommodate crystals with various load capacitance requirements and to slightly adjust the frequency of the crystal oscillator. This latter function can be used to compensate for crystal production tolerances. Utilizing the on-chip temperature sensor and suitable control software even the temperature dependency of the crystal can be canceled.

The crystal load capacitance is programmed using register 09h. The typical value of the total on-chip (internal) capacitance Cint can be calculated as follows:

Cint = 1.8 pF + 0.085 pF x xlc[6:0] + 3.7 pF x xtalshift

Note that the course shift bit xtalshift is not binary with xlc[6:0]. The total load capacitance Cload seen by the crystal can be calculated by adding the sum of all external parasitic PCB capacitances Cext to Cint. If the maximum value of Cint (16.3 pF) is not sufficient, an external capacitor can be added for exact tuning. See more on this, calculating Cext and crystal selection guidelines in "11. Application Notes" on page 82.

If AFC is disabled then the synthesizer frequency may be further adjusted by programming the Frequency Offset field fo[9:0]in "Register 73h. Frequency Offset 1" and "Register 74h. Frequency Offset 2", as discussed in "3.6. Frequency Control" on page 27.

The crystal oscillator frequency is divided down internally and may be output to the microcontroller through one of the GPIO pins for use as the System Clock. In this fashion, only one crystal oscillator is required for the entire system and the BOM cost is reduced. The available clock frequencies (i.e., internal division ratios) and the GPIO configuration are discussed further in "8.2. Microcontroller Clock" on page 56.

The Si4432 may also be driven with an external 30 MHz clock signal through the XOUT pin.

5.9. Regulators

There are a total of six regulators integrated onto the Si4432. With the exception of the IF and Digital all regulators are designed to operate with only internal decoupling. The IF and Digital regulators both require an external 1 μ F decoupling capacitor. All of the regulators are designed to operate with an input supply voltage from +1.8 to +3.6 V, and produce a nominal regulated output voltage of $+1.7$ V ± 5 %. The internal circuitry nominally operates from this regulated +1.7 V supply. The output stage of the of PA is not connected internally to a regulator and is connected directly to the battery voltage.

A supply voltage should only be connected to the VDD pins. No voltage should be forced on the IF or DIG regulator outputs.

6. Data Handling and Packet Handler

6.1. RX and TX FIFOs

Two 64 byte FIFOs are integrated into the chip, one for RX and one for TX, as shown in Figure 16. "Register 7Fh. FIFO Access" is used to access both FIFOs. A burst write, as described in "3.1. Serial Peripheral Interface (SPI)" on page 19, to address 7Fh will write data to the TX FIFO. A burst read from address 7Fh will read data from the RX FIFO.

Figure 16. FIFO Thresholds

The TX FIFO has two programmable thresholds. An interrupt event occurs when the data in the TX FIFO reaches these thresholds. The first threshold is the FIFO Almost Full threshold, txafthr[5:0]. The value in this register corresponds to the desired threshold value in number of bytes. When the data being filled into the TX FIFO reaches this threshold limit, an interrupt to the microcontroller is generated so the chip can enter TX mode to transmit the contents of the TX FIFO. The second threshold for TX is the FIFO Almost Empty Threshold, txaethr[5:0]. When the data being shifted out of the TX FIFO reaches the Almost Empty threshold an interrupt will be generated. The microcontroller will need to switch out of TX mode or fill more data into the TX FIFO. The Transceiver may be configured so that when the TX FIFO is empty the chip will automatically move to the Ready state. In this mode the TX FIFO Almost Empty Threshold may not be useful. This functionality is set by the ffidle bit in "Register 08h. Operating Mode and Function Control 2," on page 96.

The RX FIFO has one programmable threshold called the FIFO Almost Full Threshold, rxafthr[5:0]. When the incoming RX data reaches the Almost Full Threshold an interrupt will be generated to the microcontroller via the nIRQ pin. The microcontroller will then need to read the data from the RX FIFO.

Both the TX and RX FIFOs may be cleared or reset with the ffclrtx and ffclrrx bits in "Register 08h. Operating Mode and Function Control 2," on page 96. All interrupts may be enabled by setting the Interrupt Enabled bits in "Register 05h. Interrupt Enable 1" and "Register 06h. Interrupt Enable 2," on page 94. If the interrupts are not enabled the function will not generate an interrupt on the nIRQ pin but the bits will still be read correctly in the Interrupt Status registers.

6.2. Packet Configuration

When using the FIFOs, automatic packet handling may be enabled for TX mode, RX mode, or both. "Register 30h. Data Access Control" through "Register 4Bh. Received Packet Length," on page 128 control the configuration, status, and decoded RX packet data for Packet Handling. The usual fields for network communication (such as preamble, synchronization word, headers, packet length, and CRC) can be configured to be automatically added to the data payload. The fields needed for packet generation normally change infrequently and can therefore be stored in registers. Automatically adding these fields to the data payload greatly reduces the amount of communication between the microcontroller and the Si4432 and therefore also reduces the required computational power of the microcontroller.

The general packet structure is shown in Figure 17. The length of each field is shown below the field. The preamble pattern is always a series of alternating ones and zeroes, starting with a one. All the fields have programmable lengths to accommodate different applications. The most common CRC polynominals are available for selection.

Figure 17. Packet Structure

An overview of the packet handler configuration registers is shown in Table 14. A complete register description can be found in "12.1. Complete Register Table and Descriptions".

6.3. Packet Handler TX Mode

If the TX packet length is set the packet handler will send the number of bytes in the packet length field before returning to ready mode and asserting the packet sent interrupt. To resume sending data from the FIFO the microcontroller needs to command the chip to re-enter TX mode Figure 18 provides an example transaction where the packet length is set to three bytes.

6.4. Packet Handler RX Mode

6.4.1. Packet Handler Disabled

When the packet handler is disabled certain portions of the packet handler are still required. Proper modem operation requires preamble and sync, as shown in Figure 19. Bits after sync will be treated as raw data with no qualification. This mode allows for the creation of a custom packet handler when the automatic qualification parameters are not sufficient. Manchester encoding is supported but the use of data whitening, CRC, or header checks is not.

6.4.2. Packet Handler Enabled

When the packet handler is enabled, all the fields of the packet structure need to be configured. If multiple packets are desired to be stored in the FIFO, then there are options available for the different fields that will be stored into the FIFO. Figure 20 demonstrates the options and settings available when multiple packets are enabled. Figure 21 demonstrates the operation of fixed packet length and correct/incorrect packets.

Figure 20. Multiple Packets in RX Packet Handler

Figure 21. Multiple Packets in RX with CRC or Header Error

Table 14. Packet Handler Registers

6.5. Data Whitening, Manchester Encoding, and CRC

Data whitening can be used to avoid extended sequences of 0s or 1s in the transmitted data stream to achieve a more uniform spectrum. When enabled, the payload data bits are XORed with a pseudorandom sequence output from the built-in PN9 generator. The generator is initialized at the beginning of the payload. The receiver recovers the original data by repeating this operation. Manchester encoding can be used to ensure a dc-free transmission and good synchronization properties. When Manchester encoding is used, the effective datarate is unchanged but the actual datarate (preamble length, etc.) is doubled due to the nature of the encoding. The effective datarate when using Manchester encoding is **limited to 64 kbps**. Data Whitening and Manchester encoding can be selected with "Register 70h. Modulation Mode Control 1". The CRC is configured via "Register 30h. Data Access Control".

Figure 22. Operation of Data Whitening, Manchester Encoding, and CRC

6.6. Preamble Detector

The Si4432 has integrated automatic preamble detection. The preamble length is configurable from 1–256 bytes using the prealen[7:0] field in "Register 33h. Header Control 2" and "Register 34h. Preamble Length", as described in "6.2. Packet Configuration". The preamble detection threshold, preath[4:0] as set in "Register 35h. Preamble Detection Control 1", is in units of 4 bits. The preamble detector searches for a preamble pattern with a length of preath[4:0].

When a false preamble detect occurs, the receiver will continuing searching for the preamble when no sync word is detected.

The Preamble Detector output may be programmed onto one of the GPIOs or read in the Interrupt Status registers.

6.7. Preamble Length

The required preamble length threshold will depend on when the receive mode is entered in relation to the transmitted packet. When the receiver is enabled long before the arrival of the packet, then a short preamble detection threshold might result in false detects on the received noise before the actual preamble arrives. In this case, it is recommended to program a 20 bit preamble detection threshold. A shorter Preamble Detection Threshold might be chosen when occasional false detects are tolerable. When antenna diversity is enabled, it is advised to use a 20 bit preamble detection threshold. When the receiver is synchronously enabled just before the start of the packet, then a shorter preamble detection threshold might be chosen (e.g., 8 bit).

The required preamble length is determined from the sum of the receiver settling time and the preamble detection threshold. The receiver settling time is listed in Table 15.

Table 15. Minimum Receiver Settling Time

Note: The recommended preamble length and the preamble detection threshold may be shortened when occasional packet errors are tolerable.

6.8. Invalid Preamble Detector

When scanning channels in a Frequency Hopping System, it is desirable to determine if a channel is valid in the minimum amount of time. The preamble detector can output an invalid preamble detect signal. When an error is detected in the preamble, the Invalid Preamble Detect signal (nPQD) is asserted, indicating an invalid channel. The signal can be used to qualify the channel without requiring the full preamble to be received. The Preamble Detect and Invalid Preamble Detect signals are available in "Register 03h. Interrupt/Status 1" and "Register 04h. Interrupt/Status 2," on page 91.

The Invalid Preamble Detector issues an interrupt when no valid preamble signal is found. After the receiver is enabled, the Invalid Preamble Detector will be held low for 16 Tb (Tb is the time of the bit duration) to allow the receiver to settle. The 16 Tb is a fixed time which will work with a 4-byte Preamble (or longer) when AFC is enabled, or a 3-byte preamble (or longer) when AFC is disabled. The invalid preamble detect interrupt can be useful to save power and speed-up search in receive mode.

It is advised to disable the invalid preamble interrupt when Antenna Diversity is enabled. The Invalid Preamble Detect interrupt may be triggered during the Antenna Diversity algorithm if one of the antennas is weak but the other is capable of still receiving the signal if the Antenna Diversity algorithm is allowed to complete.

6.9. TX Retransmission and Auto TX

The Si4432 is capable of automatically retransmitting the last packet in the FIFO if no additional packets were loaded into the TX FIFO. Automatic Retransmission is achieved by entering the TX state with the txon bit set. This feature is useful for Beacon transmission or when retransmission is required due to the absence of a valid acknowledgement. Only packets that fit completely in the TX FIFO are valid for retransmit. When it is necessary to transmit longer packets, the TX FIFO uses the circular read/write capability.

An Automatic Transmission is also available. When autotx = 1 the transceiver will enter automatically TX State when the TX FIFO is almost full. When the TX FIFO is empty the transceiver will automatically return to the IDLE State.

7. RX Modem Configuration

7.1. Modem Settings for FSK and GFSK

The modem performs channel selection and demodulation in the digital domain. The channel filter bandwidth is configurable from 620 to 2.6 kHz. The data-rate, modulation index, and bandwidth are set via registers 1C-25. The modulation index is equal to 2 times the peak deviation divided by the data rate (Rb).

Table 16 gives the modem register settings for various common data-rates. Select the desired data-rate (Rb), and Deviation (Fd) to determine the proper register settings. For data-rates and modulation types not listed in the table a calculator tool within WDS can be used.

When Manchester coding is disabled, the required channel filter bandwidth is calculated as BW = $2 \times (Fd + 0.25Rb)$ where Fd is the frequency deviation and Rb is the data rate. For modulation indices below 1 the required channel filter bandwidth is calculated as BW = Fd + Rb. The channel filter needs to be increased when the frequency offset between transmitter and receiver is more than half the channel filter bandwidth. In this case it is recommended to enable the AFC and choose the IF bandwidth equal to 2 x frequency offset.

Table 16. RX Modem Configurations for FSK and GFSK

7.1.1. Advanced FSK and GFSK Settings

In nearly all cases, the information in Table 16, "RX Modem Configurations for FSK and GFSK," on page 49 can be used to determine the required FSK and GFSK modem parameters. The section includes a more detailed discussion of the various modem parameters to allow for experienced designers to further configure the modem performance.

In FSK or GFSK mode the receiver can handle a wide range of modulation indices ranging from 0.5 up to 32. The modulation index (h) is defined by the following:

$$
h = \frac{2 \times Fd}{Rb \times (1 + \text{emanch})}
$$

When the modulation index is 1 or higher the modulation bandwidth can be approximated by the following equation:

$$
BW_{\text{mod}} = \left(\frac{Rb}{2} \times (1 + \text{emmand}) + 2 \times Fd\right)
$$

When the modulation index is lower than 1 the modulation bandwidth can be approximated by the following:

$$
BW_{\text{mod}} = (Rb \times (1 + \text{emmand}) + \text{Fd})
$$

Where BW_{mod} is an approximation of the modulation bandwidth in kHz, Rb is the payload bit rate in kbps, Fd is the frequency deviation of the received GFSK/FSK signal in kHz and enmanch is the Manchester Coding parameter (see Reg. 70h, enmach is 1 when Manchester coding is enabled, enmanch is 0 when disabled).

The bandwidth of the channel select filter in the receiver might need some extra bandwidth to cope with tolerances in transmit and receive frequencies which depends on the tolerances of the applied crystals. When the relative frequency error (F_{error}) between transmitter and receiver is less than half the modulation bandwidth (BW_{mod}) then the AFC will correct the frequency error without needing extra bandwidth. When the frequency error exceeds $BW_{mod}/2$ then some extra bandwidth will be needed to assure proper AFC operation under worst case conditions. When the AFC is enabled it is recommended to set the bandwidth of the channel select filter ($BW_{ch-seil}$) according to the formulas below:

$$
F_{error} \leq \frac{BW_{\text{mod}}}{2} \Rightarrow BW_{ch-sel} = BW_{\text{mod}}
$$

$$
F_{error} > \frac{BW_{\text{mod}}}{2} \Rightarrow BW_{ch-sel} = 2 \times F_{error}
$$

When the AFC is disabled it is recommended to set the bandwidth of the channel select filter (BW_{ch-sei}) according to the following:

$$
BW_{ch-sel} = BW_{\text{mod}} + 2 \times F_{error}
$$

When the required bandwidth (BW) is calculated then the three filter parameters, ndec_exp, dwn3_bypass and filset, can be found from the table below. When the calculated bandwidth value is not exactly available then select the higher available bandwidth closest to the calculated bandwidth.

Table 17. Filter Bandwidth Parameters

7.2. Modem Settings for OOK

The Si4432 is configured for OOK mode by setting the modtyp[1:0] field to OOK in "Register 71h. Modulation Mode Control 2". In OOK mode, the following parameters can be configured: data rate, manchester coding, channel filter bandwidth, and the clock recovery oversampling rate.

The required data rate (Rb) is configured via the txdr[15:0] field in "Register 6Eh. TX Data Rate 1" and "Register 6Fh. TX Data Rate 0". For data rates < 30 kbps, "txdtrscale" in "Register 70h. Modulation Mode Control 1" should be set to 1 for increased data rate precision. Manchester coding is enabled by setting enmanch in Register 70h.

The receive channel select filter bandwidth is configured via "Register 1Ch. IF Filter Bandwidth". The register settings for the available channel bandwidth bandwidths are shown in Table 18.

Table 18. Channel Filter Bandwidth Settings

The proper settings for ndec[2:0] are listed in Table 19 where Rb is the data rate (Rb) which is doubled when Manchester coding is enabled.

Table 19. ndec[2:0] Settings

The clock recovery oversampling rate is set via rxosr[10:0] in "Register 20h. Clock Recovery Oversampling Rate" and "Register 21h. Clock Recovery Offset 2".

ndec_exp and dwn3_bypass together with the receive data rate (Rb) are used to calculate rxosr:

$$
rxosr = \frac{500 \times (1 + 2 \times dwn3 \text{ } \text{ }bypass)}{2^{ndec_exp-3} \times Rb \times (1 + \text{ }emanch)}
$$

Where: Rb is in kbps and enmanch is the Manchester Coding parameter. The resulting rxdr[10:0] value should be rounded to an integer hexadecimal number.

The clock recovery offset ncoff[19:0] in "Register 21h. Clock Recovery Offset 2", "Register 22h. Clock Recovery Offset 1", and "Register 23h. Clock Recovery Offset 0" is calculated as follows:

$$
ncoff = \frac{Rb \times (1 + enamch) \times 2^{20 + ndec_exp}}{500 \times (1 + 2 \times dwn3 _ bypass)}
$$

Where: Rb is in kbps.

The clock recovery gain crgain[10:0] in "Register 24h. Clock Recovery Timing Loop Gain 1" and "Register 25h. Clock Recovery Timing Loop Gain 0" is calculated as follows:

$$
crgan = 2 + \frac{2^{16}}{rxosr}
$$

RX Modem Setting Examples for OOK (Manchester Disabled)												
Appl Parameters		Register Values										
Rb	RX BW	dwn3_bypass	ndec_exp[2:0]	fileset[3:0]	rxosr[10:0]	ncoff[19:0]	crgain[10:0]					
[kbps]	[kHz]	1Ch	1Ch	1Ch	20,21h	21,22,23h	24,25h					
1.2	75	0	4	1	0D ₀	09D49	13D					
1.2	110	0	4	5	0D ₀	09D49	13D					
1.2	335	1	4	8	271	0346E	06B					
1.2	420	1	4	A	271	0346E	06B					
1.2	620		4	E	271	0346E	06B					
2.4	335		3	8	271	0346E	06B					
4.8	335		$\overline{2}$	8	271	0346E	06B					
9.6	335	1		8	271	0346E	06B					
10	335	1		8	258	0369D	06F					
15	335			8	190	051EC	0A6					
19.2	335	и		8	139	068DC	0D ₃					
20	335	1		8	12C	06D3A	0DC					
30	335			8	0C8	0A3D7	14A					
38.4	335	1	1	8	09C	0D1B7	1A6					
40	335	1		8	096	0DA74	1B7					

Table 20. RX Modem Configuration for OOK with Manchester Disabled

Table 21. RX Modem Configuration for OOK with Manchester Enabled

8. Auxiliary Functions

8.1. Smart Reset

The Si4432 contains an enhanced integrated SMART RESET or POR circuit. The POR circuit contains both a classic level threshold reset as well as a slope detector POR. This reset circuit was designed to produce reliable reset signal in any circumstances. Reset will be initiated if any of the following conditions occur:

- Initial power on, when VDD starts from 0V: reset is active till VDD reaches V_{RR} (see table);
- When VDD decreases below V_{LD} for any reason: reset is active till VDD reaches V_{RR} again;
- A software reset via "Register 08h. Operating Mode and Function Control 2," on page 96: reset is active for time TSWRST
- On the rising edge of a VDD glitch when the supply voltage exceeds the following time functioned limit:

Figure 23. POR Glitch Parameters

The reset will initialize all registers to their default values. The reset signal is also available for output and use by the microcontroller by using the default setting for GPIO_0. The inverted reset signal is available by default on GPIO_1.

8.2. Microcontroller Clock

The crystal oscillator frequency is divided down internally and may be output to the microcontroller through GPIO2. This feature is useful to lower BOM cost by using only one crystal in the system. The system clock frequency is selectable from one of 8 options, as shown below. Except for the 32.768 kHz option, all other frequencies are derived by dividing the Crystal Oscillator frequency. The 32.768 kHz clock signal is derived from an internal RC Oscillator or an external 32 kHz Crystal, depending on which is selected. The GPIO2 default is the microcontroller clock with a 1 MHz microcontroller clock output.

If the microcontroller clock option is being used there may be the need of a System Clock for the microcontroller while the Si4432 is in SLEEP mode. Since the Crystal Oscillator is disabled in SLEEP mode in order to save current, the low-power 32.768 kHz clock can be automatically switched to become the microcontroller clock. This feature is called Enable Low Frequency Clock and is enabled by the enlfc bit. When enlfc = 1 and the chip is in SLEEP mode then the 32.768 kHz clock will be provided to the microcontroller as the System Clock, regardless of the setting of mclk[2:0]. For example, if mclk[2:0] = 000, 30 MHz will be provided through the GPIO output pin to the microcontroller as the System Clock in all IDLE, TX, or RX states. When the chip is commanded to SLEEP mode, the System Clock will become 32.768 kHz.

Another available feature for the microcontroller clock is the Clock Tail, clkt[1:0]. If the Enable Low Frequency Clock feature is not enabled (enlfc = 0), then the System Clock to the microcontroller is disabled in SLEEP mode. However, it may be useful to provide a few extra cycles for the microcontroller to complete its operation prior to the shutdown of the System Clock signal. Setting the clkt[1:0] field will provide additional cycles of the System Clock before it shuts off.

If an interrupt is triggered, the microcontroller clock will remain enabled regardless of the selected mode. As soon as the interrupt is read the state machine will then move to the selected mode. For instance, if the chip is commanded to Sleep mode but an interrupt has occurred the 30 MHz XTAL will not disable until the interrupt has been cleared.

8.3. General Purpose ADC

An 8-bit SAR ADC is integrated onto the chip for general purpose use, as well as for digitizing the temperature sensor reading. "Register 0Fh. ADC Configuration," on page 103 must be configured depending on the use of the GP ADC before use. The architecture of the ADC is demonstrated in Figure 24. First the input of the ADC must be selected by setting the ADCSEL[2:0] depending on the use of the ADC. For instance, if the ADC is going to be used to read out the internal temperature sensor, then ADCSEL[2:0] should be set to 000. Next, the input reference voltage to the ADC must be chosen. By default, the ADC uses the bandgap voltage as a reference so the input range of the ADC is from 0-1.02 V with an LSB resolution of 4 mV (1.02/255). Changing the ADC reference will change the LSB resolution accordingly.

Every time the ADC conversion is desired, the ADCStart bit in "Register 0Fh. ADC Configuration," on page 103 must be set to 1. This is a self clearing bit that will be cleared at the end of the conversion cycle of the ADC. The conversion time for the ADC is 350 us. After the 350 us or when the ADCstart/busy bit is cleared, then the ADC value may be read out of "Register 11h. ADC Value". Setting the "Register 10h. ADC Sensor Amplifier Offset", ADC Sensor Amplifier Offset is only necessary when the ADC is configured to used as a Bridge Sensor as described in the following section.

Figure 24. General Purpose ADC Architecture

8.3.1. ADC Differential Input Mode—Bridge Sensor Example

The differential input mode of ADC8 is designed to directly interface any bridge-type sensor, which is demonstrated in the figure below. As seen in the figure the use of the ADC in this configuration will utilize two GPIO pins. The supply source of the bridge and chip should be the same to eliminate the measuring error caused by battery discharging. For proper operation one of the VDD dependent references (VDD/2 or VDD/3) should be selected for the reference voltage of ADC8. VDD/2 reference should be selected for VDD lower than 2.7 V, VDD/3 reference should be selected for VDD higher than 2.7 V. The differential input mode supports programmable gain to match the input range of ADC8 to the characteristic of the sensor and VDD proportional programmable offset adjustment to compensate the offset of the sensor.

The adcgain[1:0] bits in "Register 0Eh. I/O Port Configuration" determine the gain of the differential/single ended amplifier. This is used to fit the input range of the ADC8 to bridge sensors having different sensitivity:

Note: The input range is the differential voltage measured between the selected GPIO pins corresponding to the full ADC range (255).

The gain is different for different VDD dependent references so the reference change has no influence on input range and digital measured values.

The differential offset can be coarse compensated by the adcoffs[3:0] bits found in "Register 11h. ADC Value". Fine compensation should be done by the microcontroller software. The main reason for the offset compensation is to shift the negative offset voltage of the bridge sensor to the positive differential voltage range. This is essential as the differential input mode is unipolar. The offset compensation is VDD proportional, so the VDD change has no influence on the measured value.

Figure 26. ADC Differential Input Offset for Sensor Offset Coarse Compensation

8.4. Temperature Sensor

An analog temperature sensor is integrated into the chip. The temperature sensor will be automatically enabled when the temperature sensor is selected as the input of the ADC or when the analog temp voltage is selected on the analog test bus. The temperature sensor value may be digitized using the general-purpose ADC and read out over the SPI through "Register 10h. ADC Sensor Amplifier Offset". The range of the temperature sensor is selectable to configure to the desired application and performance. The table below demonstrates the settings for the different temperature ranges and performance.

To use the Temp Sensor:

- 1. Set input for ADC to be Temperature Sensor, "Register 0Fh. ADC Configuration"—adcsel[2:0] = 000
- 2. Set Reference for ADC, "Register 0Fh. ADC Configuration"—adcref $[1:0] = 00$
- 3. Set Temperature Range for ADC, "Register 12h. Temperature Sensor Calibration"—tsrange[1:0]
- 4. Set entsoffs = 1, "Register 12h. Temperature Sensor Calibration"
- 5. Trigger ADC Reading, "Register 0Fh. ADC Configuration"—adcstart = 1
- 6. Read-out Value-Read Address in "Register 11h. ADC Value"

entoff	tsrange[1]	tsrange[0]	Temp. range	Unit	Slope	ADC8 LSB			
			-6464	°C	8 mV °C	0.5 °C			
			-64 192	°C	4 mV/ $^{\circ}$ C	1° C			
			0128	°C	8 mV °C	0.5 °C			
			-40216	P	4 mV/ \degree F	1 °F			
0^*			0341	°K	3 mV ^o K	1.333 K			
*Netauration comparature made no temperature objet. This mede is only fer test purposes. DOD value of									

Table 23. Temperature Sensor Range

***Note:** Absolute temperature mode, no temperature shift. This mode is only for test purposes. POR value of EN_TOFF is 1.

Control to adjust the temperature sensor accuracy is available by adjusting the bandgap voltage. By enabling the envbgcal and using the vbgcal[3:0] bits to trim the bandgap the temperature sensor accuracy may be fine tuned in the final application. The slope of the temperature sensor is very linear and monotonic but the exact accuracy or offset in temperature is difficult to control better than ± 10 °C. With the vbgtrim or bandgap trim though the initial temperature offset can be easily adjusted and be better than ±3 °C.

The different ranges for the temperature sensor and ADC8 are demonstrated in Figure 27. The value of the ADC8 may be translated to a temperature reading by ADC8Value x ADC8 LSB + Lowest Temperature in Temp Range. For instance for a tsrange = 00, Temp = ADC8Value $x = 0.5 - 64$.

Figure 27. Temperature Ranges using ADC8

8.5. Low Battery Detector

A low battery detector (LBD) with digital read-out is integrated into the chip. A digital threshold may be programmed into the lbdt[4:0] field in "Register 1Ah. Low Battery Detector Threshold". When the digitized battery voltage reaches this threshold an interrupt will be generated on the nIRQ pin to the microcontroller. The microcontroller will then need to verify the interrupt by reading "Register 03h. Interrupt/Status 1" and "Register 04h. Interrupt/Status 2," on page 91.

If the LBD is enabled while the chip is in SLEEP mode, it will automatically enable the RC oscillator which will periodically turn on the LBD circuit to measure the battery voltage. The battery voltage may also be read out through "Register 1Bh. Battery Voltage Level" at any time when the LBD is enabled. The Low Battery Detect function is enabled by setting enlbd=1 in "Register 07h. Operating Mode and Function Control 1".

The LBD output is digitized by a 5-bit ADC. When the LBD function is enabled, enlbd = 1 in "Register 07h. Operating Mode and Function Control 1", the battery voltage may be read at anytime by reading "Register 1Bh. Battery Voltage Level". A Battery Voltage Threshold may be programmed to register 1Ah. When the battery voltage level drops below the battery voltage threshold an interrupt will be generated on nIRQ pin to the microcontroller if the LBD interrupt is enabled in "Register 06h. Interrupt Enable 2," on page 94. The microcontroller will then need to verify the interrupt by reading the interrupt status register, Addresses 03 and 04H. The LSB step size for the LBD ADC is 50 mV, with the ADC range demonstrated in the table below. If the LBD is enabled the LBD and ADC will automatically be enabled every 1 s for approximately 250 µs to measure the voltage which minimizes the current consumption in Sensor mode. Before an interrupt is activated four consecutive readings are required.

$BatteryVoltage = 1.7 + 50mV \times ADCValue$

8.6. Wake-Up Timer

The chip contains an integrated wake-up timer which periodically wakes the chip from SLEEP mode. The wake-up timer runs from the internal 32.768 kHz RC Oscillator. The wake-up timer can be configured to run when in SLEEP mode. If enwt = 1 in "Register 07h. Operating Mode and Function Control 1" when entering SLEEP mode, the wake-up timer will count for a time specified by the Wake-Up Timer Period in Registers 10h–12h. At the expiration of this period an interrupt will be generated on the nIRQ pin if this interrupt is enabled. The microcontroller will then need to verify the interrupt by reading the Interrupt Status Registers 03h-04h. The wake-up timer value may be read at any time by the wtv[15:0] read only registers 13h-14h.

The formula for calculating the Wake-Up Period is the following:

$$
WUT = \frac{32 \times M \times 2^{R-D}}{32.768} \, \text{ms}
$$

Use of the D variable in the formula is only necessary if finer resolution is required than the R value gives.

There are two different methods for utilizing the wake-up timer (WUT) depending on if the WUT interrupt is enabled in "Register 06h. Interrupt Enable 2," on page 94. If the WUT interrupt is enabled then nIRQ pin will go low when the timer expires. The chip will also change state so that the 30 M XTAL is enabled so that the microcontroller clock output is available for the microcontroller to use process the interrupt. The other method of use is to not enable the WUT interrupt and use the WUT GPIO setting. In this mode of operation the chip will not change state until commanded by the microcontroller. The two different modes of operation of the WUT are demonstrated in Figure 28.

A 32 kHz XTAL may also be used for better timing accuracy. By setting the x32 ksel bit in 07h, GPIO0 is automatically reconfigured so that an external 32 kHz XTAL may be connected to this pin. In this mode, the GPIO0 is extremely sensitive to parasitic capacitance, so only the XTAL should be connected to this pin and the XTAL should be physically located as close to the pin as possible. Once the x32 ksel bit is set, all internal functions such as WUT, micro-controller clock, and LDC mode will use the 32 K XTAL and not the 32 kHz RC oscillator.

Interrupt Enable enwut=1 (Reg 06h)

Figure 28. WUT Interrupt and WUT Operation

8.7. Low Duty Cycle Mode

The Low Duty Cycle Mode is available to automatically wake-up the receiver to check if a valid signal is available. The basic operation of the low duty cycle mode is demonstrated in the figure below. If a valid preamble or sync word is not detected the chip will return to sleep mode until the beginning of a new WUT period. If a valid preamble and sync are detected the receiver on period will be extended for the low duty cycle mode duration (TLDC) to receive all of the packet. The time of the TLDC is determined by the formula below:

Figure 29. Low Duty Cycle Mode

8.8. GPIO Configuration

Three general purpose IOs (GPIOs) are available. Numerous functions such as specific interrupts, TRSW control, Microcontroller Output, etc. can be routed to the GPIO pins as shown in the tables below. When in Shutdown mode all the GPIO pads are pulled low.

Note: The ADC should not be selected as an input to the GPIO in Standby or Sleep Modes and will cause excess current consumption.

The GPIO settings for GPIO1 and GPIO2 are the same as for GPIO0 with the exception of the 00000 default setting. The default settings for each GPIO are listed below:

The diagrams in Figure 30 show two different configurations/usage of the GPIO. In Configuration A an external sensor is used and the GPIO is configured as an input with the 00101 External Interrupt, Rising Edge setting. When the sensor is triggered the nIRQ pin will go high and the microcontroller will be able to read the interrupt register and know that an event occurred on the sensor. The advantage of this configuration is that it saves a microcontroller pin. This application utilizes the high output power so a TRSW is required.

In Configuration B, the chip is configured to provide the System Clock output to the microcontroller so that only one crystal is needed in the system, therefore reducing the BOM cost. For the TX Data Source, Direct Mode is used because long packets are desired with a unique packet handling format already implemented in the microcontroller. In this configuration the TX Data Clock is configured onto GPIO0, the TX Data is configured onto GPIO1, and the Microcontroller System Clock output is configured onto GPIO2. In this application only the lowest output power setting is required so no TRSW is needed.

For a complete list of the available GPIO's see "Register 0Ch. GPIO Configuration 1," on page 100, "Register 0Dh. GPIO Configuration 2," on page 101, and "Register 0Eh. I/O Port Configuration," on page 102.

GPIO Configuration B

Figure 30. GPIO Usage Examples

8.9. Antenna-Diversity

To mitigate the problem of frequency-selective fading due to multi-path propagation, some transceiver systems use a scheme known as Antenna Diversity. In this scheme, two antennas are used. Each time the transceiver enters RX mode the receive signal strength from each antenna is evaluated. This evaluation process takes place during the preamble portion of the packet. The antenna with the strongest received signal is then used for the remainder of that RX packet. The same antenna will also be used for the next corresponding TX packet.

This chip fully supports Antenna Diversity with an integrated Antenna Diversity Control Algorithm. By setting GPIOx[4:0] = 10111 and 11000, the required signal needed to control an external SPDT RF switch (such as PIN diode or GaAs switch) is made available on the GPIOx pins. The operation of these switches is programmable to allow for different Antenna Diversity architectures and configurations. The antdiv[2:0] register is found in register 08h. The GPIO pin is capable of sourcing up to 5 mA of current, so it may be used directly to forward-bias a PIN diode if desired.

When the arrival of the packet is unknown by the receiver the antenna diversity algorithm (antdiv[2:0] = 100 or 101) will detect both packet arrival and selects the antenna with the strongest signal. The recommended preamble length to obtain good antenna selection is 8 bytes. A special antenna diversity algorithm (antdiv[2:0] = 110 or 111) is included that allows for shorter preamble for TDMA like systems where the arrival of the packet is synchronized to the receiver enable. The recommended preamble length to obtain good antenna selection for synchronized mode is 4 bytes.

Table 24. Antenna Diversity Control

8.10. TX/RX Switch Control

When using the maximum output power of +20 dBm a TX/RX Switch (TRSW) may be required. The control for the switch with the proper timing will be available on the GPIO pins. See application schematics for various options using a TX/RX Switch.

8.11. RSSI and Clear Channel Assessment

The RSSI (Received Signal Strength Indicator) signal is an estimate of the signal strength in the channel to which the receiver is tuned. The RSSI value can be read from an 8-bit register with 0.5 dB resolution per bit. Figure 31 demonstrates the relationship between input power level and RSSI value. The RSSI may be read at anytime, but an incorrect error may rarely occur. The RSSI value may be incorrect if read during the update period. The update period is approximately 10 ns every 4 Tb. For 10 kbps, this would result in a 1 in 40,000 probability that the RSSI may be read incorrectly. This probability is extremely low, but to avoid this, one of the following options is recommended: majority polling, reading the RSSI value within 1 Tb of the RSSI interrupt, or using the RSSI threshold described in the next paragraph for Clear Channel Assessment.

For Clear Channel Assessment a threshold is programmed into rssith[7:0] in "Register 27h. RSSI Threshold for Clear Channel Indicator". After the RSSI is evaluated in the preamble, a decision is made if the signal strength on this channel is above or below the threshold. If the signal strength is above the programmed threshold then a 1 will be shown in the RSSI status bit in "Register 02h. Device Status", "Register 04h. Interrupt/Status 2", or configurable GPIO (GPIOx[3:0] = 1110).

Figure 31. RSSI Value vs. Input Power

9. Reference Design

Figure 32. Split RF I/Os with Separated TX and RX Connectors-Schematic **Figure 32. Split RF I/Os with Separated TX and RX Connectors—Schematic**

Si4432

Figure 33. Common TX/RX Connector with RF Switch-Schematic **Figure 33. Common TX/RX Connector with RF Switch—Schematic**

Si4432

Figure 34. Antenna Diversity Reference Design-Schematic **Figure 34. Antenna Diversity Reference Design—Schematic**

Table 27. Antenna Diversity Bill of Materials

10. Measurement Results

Note: Sensitivity is BER measured, GFSK modulation, BT = 0.5, H = 1.

Figure 35. Sensitivity vs. Data Rate

Figure 36. Receiver Selectivity

Figure 37. TX Output Power vs. VDD Voltage

Figure 38. TX Output Power vs Temperature

Date: 04-22-08 Time: 02:28 PM

Figure 39. TX Modulation (40 kbps, 20 kHz Deviation)

Figure 40. TX Unmodulated Spectrum (917 MHz)

Figure 41. TX Modulated Spectrum (917 MHz, 40 kbps, 20 kHz Deviation, GFSK)

Date: 04-23-08 Time: 04:03 PM

Figure 42. Synthesizer Settling Time for 1 MHz Jump Settled within 10 kHz

Figure 43. Synthesizer Phase Noise (VCOCURR = 11)

11. Application Notes

This section offers a brief introduction to a number of application related topics. Further recommended reading can be found in our related application notes at http://www.silabs.com.

11.1. Crystal Selection

The recommended crystal parameters are given in Table 28.

Table 28. Recommended Crystal Parameters

The internal XTAL oscillator will work over a range for the parameters of ESR, CL, C0, and ppm accuracy. Extreme values may affect the XTAL start-up and sensitivity of the link. For questions regarding the use of a crystal parameters greatly deviating from the recommend values listed above, please contact customer support.

The crystal used for engineering evaluation and the reference design is the SIWARD $-$ SX2520 $-$ 30.0 MHz $-$ 12.0R. Ordering number XTL581200JIG.

11.2. Layout Practice

The following are some general best practice guidelines for PCB layout using the EZRadioPro devices:

- \blacksquare Bypass capacitors should be placed as close as possible to the pin.
- TX/RX matching/layout should mimic reference as much as possible. Failing to do so may cause loss inperformance.
- A solid ground plane is required on the backside of the board under TX/RX matching components
- Crystal should be placed as close as possible to the XIN/XOUT pins and should not have VDD traces running underneath or near it.
- The paddle on the backside of the QFN package needs solid grounding and good soldered connection
- Use GND stitch vias liberally throughout the board, especially underneath the paddle.

11.3. Matching Network Design

11.3.1. RX LNA Matching

Figure 44. RX LNA Matching

11.3.2. TX Matching and Filtering

The Si4432 features an efficient, high-power output driver allowing the device to deliver a large output power to the antenna with low current consumption. Like any high-performance PA design, certain design considerations must be taken into account when building the overall system to ensure reliable and efficient operation.

Matching networks that are not designed correctly can exhibit wide variations in load impedance resulting in excessive voltage swings at the TX pin. Load impedance can be impacted by environmental changes such as mounting location, operation while being held in the users hand, etc. These must be taken into account in determining the range of antenna impedances to which the PA can be subjected. To ensure that the combination of the matching network and antenna achieve the specified TX output power while remaining in the allowable range of output voltage swing, the following matching requirements must be observed.

The output voltage swing of the Si4432 PA depends on the supply voltage to the device, the antenna matching network, and the antenna impedance. The output voltage swing of the Si4432 at the TX pin must be kept below 6.5 V to ensure long-term reliability of the device. Depending on the maximum supply voltage to the device and the impedance presented to the chip by the antenna and matching network, a limiting resistor may be installed above pull-up inductor L1, with its value adjusted to ensure safe operation.

The impedance seen looking into the lowpass filter matching structure (e.g., L0, CM, LM, etc.) naturally becomes very large at frequencies well above the LPF cutoff frequency. As a result, the return loss seen by the PA at the harmonic frequencies is degraded, contributing to larger swings in voltage at the TX output pin. Silicon Labs recommends the addition of a harmonic termination circuit (LHARM, CHARM, RHARM) to provide an improved return loss at high frequencies, and thus further help to constrain the swing in peak voltage at the TX output pin to an acceptable value.

Figure 45. TX Matching and Filtering for Different Bands

The following table provides recommended values of the limiting resistor R_{DC} versus operating voltage and antenna return loss for some common V_{DD} and return loss combinations. For operation outside of these ranges, consult with Silicon Laboratories' applications support team.

12. Reference Material

12.1. Complete Register Table and Descriptions

Table 30. Register Descriptions

Table 30. Register Descriptions (Continued)

Register 00h. Device Type Code (DT)

Reset value = 00001000

Register 01h. Version Code (VC)

Reset value = xxxxxxxx

Register 02h. Device Status

Reset value = xxxxxxxx

Register 03h. Interrupt/Status 1

Reset value = xxxxxxxx

When any of the Interrupt/Status 1 bits change state from 0 to 1 the device will notify the microcontroller by setting the nIRQ pin LOW if it is enabled in the Interrupt Enable 1 register. The nIRQ pin will go to HIGH and all the **enabled** interrupt bits will be cleared when the microcontroller reads this address. If any of these bits is not enabled in the Interrupt Enable 1 register then it becomes a status signal that can be read anytime in the same location and will not be cleared by reading the register.

Table 31. Interrupt or Status 1 Bit Set/Clear Description

Table 32. When are Individual Status Bits Set/Cleared if not Enabled as Interrupts?

Register 04h. Interrupt/Status 2

Reset value = xxxxxxxx

When any of the Interrupt/Status Register 2 bits change state from 0 to 1 the control block will notify the microcontroller by setting the nIRQ pin LOW if it is enabled in the Interrupt Enable 2 register. The nIRQ pin will go to HIGH and all the **enabled** interrupt bits will be cleared when the microcontroller reads this address. If any of these bits is not enabled in the Interrupt Enable 2 register then it becomes a status signal that can be read anytime in the same location and will not be cleared by reading the register.

Table 33. Interrupt or Status 2 Bit Set/Clear Description

Table 34. Detailed Description of Status Registers when not Enabled as Interrupts

Register 05h. Interrupt Enable 1

Register 06h. Interrupt Enable 2

Register 07h. Operating Mode and Function Control 1

Register 09h. 30 MHz Crystal Oscillator Load Capacitance

Register 0Ah. Microcontroller Output Clock

Reset value = xx000110

Register 0Bh. GPIO Configuration 0

Register 0Ch. GPIO Configuration 1

Register 0Dh. GPIO Configuration 2

Register 0Eh. I/O Port Configuration

Register 0Fh. ADC Configuration

Register 10h. ADC Sensor Amplifier Offset

Reset value = xxxx0000

Register 11h. ADC Value

Reset value = xxxxxxxx

Register 12h. Temperature Sensor Calibration

Reset value = 00100000

Register 13h. Temperature Value Offset

Register 14h. Wake-Up Timer Period 1

Reset value = xx000000

Register 15h. Wake-Up Timer Period 2

Reset value = 00000000

Register 16h. Wake-Up Timer Period 3

Register 17h. Wake-Up Timer Value 1

Reset value = xxxxxxxx

Register 18h. Wake-Up Timer Value 2

Reset value = xxxxxxxx

Register 19h. Low-Duty Cycle Mode Duration

Register 1Ah. Low Battery Detector Threshold

Reset value = xxx10100

Register 1Bh. Battery Voltage Level

Reset value = xxxxxxxx

Register 1Ch. IF Filter Bandwidth

Reset value = 00000001

Register 1Dh. AFC Loop Gearshift Override

Register 1Eh. AFC Timing Control

Reset value = xx001000

The gear-shift register controls BCR loop gain. Before the preamble is detected, BCR loop gain is as follows:

$$
BCRLoopGain = \frac{crgain}{2^{crfas}}
$$

Once the preamble is detected, internal state machine automatically shift BCR loop gain to the following:

$$
BCRLoopGain = \frac{crgain}{2^{crslow}}
$$

crfast = 3'b000 and crslow = 3'b101 are recommended for most applications. The value of "crslow" should be greater than "crfast".

Reset value = 00000011

The oversampling rate can be calculated as rxosr = 500 kHz/(2^{ndec_exp} x RX DR). The ndec exp and the dwn3_bypass values found at Address: 1Ch - IF Filter Bandwidth register together with the receive data rate (Rb) are the parameters needed to calculate rxosr:

$$
rxosr = \frac{500 \times (1 + 2 \times dwn3 \text{ }_bypass)}{2^{ndec_exp-3} \times Rb \times (1 + \text{ }enmanch)}
$$

The Rb unit used in this equation is in kbps. The enmanch is the Manchester Coding parameter (see Reg. 70h, enmach is 1 when Manchester coding is enabled, enmanch is 0 when disabled). The number found in the equation should be rounded to an integer. The integer can be translated to a hexadecimal.

For optimal modem performance it is recommended to set the rxosr to at least 8. A higher rxosr can be obtained by choosing a lower value for ndec exp or enable dwn3 bypass. A correction in filset might be needed to correct the channel select bandwidth to the desired value. Note that when ndec exp or dwn3 bypass are changed the related parameters (rxosr, ncoff and crgain) need to be updated.

Register 20h. Clock Recovery Oversampling Rate

Reset value = 01100100

The offset can be calculated as follows:

$$
ncoff = \frac{Rb \times (1+enmanch) \times 2^{20+ndec_exp}}{500 \times (1+2 \times dwn3_bypass)}
$$

The default values for register 20h to 23h gives 40 kbps RX_DR with Manchester coding is disenabled.

Register 21h. Clock Recovery Offset 2

Register 22h. Clock Recovery Offset 1

Reset value = 01000111

Register 23h. Clock Recovery Offset 0

Reset value = 10101110

The loop gain can be calculated as crgain = 2^{16} / (rxosr x h x P), where the modulation index h = 2 x FD / RX_DR.

Register 24h. Clock Recovery Timing Loop Gain 1

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Register 25h. Clock Recovery Timing Loop Gain 0

Reset value = 10001111

Register 26h. Received Signal Strength Indicator

Reset value = 00000000

Register 27h. RSSI Threshold for Clear Channel Indicator

Register 28h. Antenna Diversity 1

Reset value = 00000000

Register 29h. Antenna Diversity 2

Register 30h. Data Access Control

Register 31h. EZMAC® Status

Register 32h. Header Control 1

Register 33h. Header Control 2

Register 34h. Preamble Length

Reset value = 00001000

Register 35h. Preamble Detection Control 1

Reset value = 00100000

Register 36h. Synchronization Word 3

Register 37h. Synchronization Word 2

Reset value = 11010100

Register 38h. Synchronization Word 1

Reset value = 00000000

Register 39h. Synchronization Word 0

Register 3Ah. Transmit Header 3

Reset value = 00000000

Register 3Bh. Transmit Header 2

Reset value = 00000000

Register 3Ch. Transmit Header 1

Register 3Dh. Transmit Header 0

Reset value = 00000000

Register 3Eh. Packet Length

Reset value = 00000000

Check Header bytes 3 to 0 are checked against the corresponding bytes in the Received Header if the check is enabled in "Register 31h. EZMAC® Status," on page 117.

Register 3Fh. Check Header 3

Reset value = 00000000

Register 40h. Check Header 2

Reset value = 00000000

Register 41h. Check Header 1

Register 42h. Check Header 0

Reset value = 00000000

Header Enable bytes 3 to 0 control which bits of the Check Header bytes are checked against the corresponding bits in the Received Header. Only those bits are compared where the enable bits are set to 1.

Register 43h. Header Enable 3

Reset value = 00000000

Register 44h. Header Enable 2

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Register 45h. Header Enable 1

Reset value = 00000000

Register 46h. Header Enable 0

Reset value = 00000000

Register 47h. Received Header 3

Register 48h. Received Header 2

Reset value = 00000000

Register 49h. Received Header 1

Reset value = 00000000

Register 4Ah. Received Header 0

Register 4Bh. Received Packet Length

Reset value = 11111111

Register 50h. Analog Test Bus Select

Table 35. Internal Analog Signals Available on the Analog Test Bus

Register 51h. Digital Test Bus Select

Reset value = 00000000

Table 36. Internal Digital Signals Available on the Digital Test Bus

Table 36. Internal Digital Signals Available on the Digital Test Bus (Continued)

Register 52h. TX Ramp Control

The total settling time (cold start) of the PLL after the calibration can be calculated as $T_{CS} = T_S + T_O$.

Register 53h. PLL Tune Time

Register 55h. Calibration Control

Reset value = x0x00100

Register 56h. Modem Test

Reset value = 00000000

Register 57h. Charge Pump Test

Register 58h. Charge Pump Current Trimming/Override

Reset value = 100xxxxx

Register 59h. Divider Current Trimming/Delta-Sigma Test

Register 5Ah. VCO Current Trimming

Reset value = 10000011

Register 5Bh. VCO Calibration/Override

Register 5Ch. Synthesizer Test

Reset value = 0x001110

Reset value = 00000000

Register 5Eh. Block Enable Override 2

Reset value = 00000000

Register 60h. Channel Filter Coefficient Address

Register 61h. Channel Filter Coefficient Value

Reset value = 00000000

Register 62h. Crystal Oscillator/Power-on-Reset Control

Reset value = xxx00100

Register 63h. RC Oscillator Coarse Calibration/Override

Reset value = 00000000

Register 64h. RC Oscillator Fine Calibration/Override

Register 65h. LDO Control Override

Reset value = 10000001

Register 66h. LDO Level Settings

Reset value = 00011101

Register 68h. Delta-Sigma ADC Tuning 2

Register 69h. AGC Override 1

Reset value = 00100000

Register 6Ah. AGC Override 2

Register 6Bh. GFSK FIR Filter Coefficient Address

Reset value = xxxxx000

Register 6Ch. GFSK FIR Filter Coefficient Value

Reset value = xxxxx000

Register 6Dh. TX Power

Reset value = xxxxxx11

Register 6Eh. TX Data Rate 1

Reset value = 00001010

The data rate can be calculated as: TX_DR = 10³ x txdr[15:0] / 2 ¹⁶ [kbps] (if address 70[5] = 0) **or** The data rate can be calculated as: TX_DR = 10³ x txdr[15:0] / 2²¹ [kbps] (if address 70[5] = 1)

Register 6Fh. TX Data Rate 0

Reset value = 00001101

Register 70h. Modulation Mode Control 1

Register 71h. Modulation Mode Control 2

Reset value = 00000000

The frequency deviation can be calculated: Fd = 625 Hz x fd[8:0].

Register 72h. Frequency Deviation

Reset value = 00100000

Note: It's recommended to use modulation index of 1 or higher (maximum allowable modulation index is 32). The modulation index is defined by 2F_N/F_R were F_D is the deviation and R_B is the data rate. When Manchester coding is enabled the modulation index is defined by $\mathsf{F}_{\mathsf{D}}\!/\mathsf{R}_{\mathsf{B}}$.

Register 73h. Frequency Offset 1

Reset value = 00000000

Reading from this register will give the AFC correction last results, not this register value.

Register 74h. Frequency Offset 2

Reset value = 00000000

Register 75h. Frequency Band Select

Reset value = 01110101

The RF carrier frequency can be calculated as follows:

f_{carrier} = (f_b+24+(f_c+f_o) / 64000) x 10000 x (hbsel+1) + (f_{hch} x f_{hs} x 10) [kHz],

where parameters f_c, f_o, f_b and hb_sel come from registers 73h–77h. Parameters f_{hch} and f_{hs} come from register 79h and 7Ah.

Register 76h. Nominal Carrier Frequency

Reset value = 10111011

Register 77h. Nominal Carrier Frequency

Reset value = 10000000

Register 79h. Frequency Hopping Channel Select

Register 7Ah. Frequency Hopping Step Size

Reset value = 00000000

Register 7Ch. TX FIFO Control 1

Reset value = 00110111

Register 7Dh. TX FIFO Control 2

Register 7Eh. RX FIFO Control

Reset value = 00110111

Register 7Fh. FIFO Access

Reset value = NA

13. Pin Descriptions: Si4432

14. Ordering Information

15. Package Outline

Figure 46 illustrates the package details for the Si4432. Table 37 lists the values for the dimensions shown in the illustration.

Figure 46. QFN-20 Package

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.

- **2.** Dimensioning and Tolerancing per ANSI Y14.5M-1994.
- **3.** This drawing conforms to the JEDEC Solid State Outline MO-220, Variation VGGD-8.
- **4.** Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

16. PCB Land Pattern

Figure 47 illustrates the PCB land pattern details for the Si4432. Table 38 lists the values for the dimensions shown in the illustration.

Figure 47. PCB Land Pattern

Notes: General

- **1.** All dimensions shown are in millimeters (mm) unless otherwise noted.
- **2.** This Land Pattern Design is based on IPC-7351 guidelines.

Notes: Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Notes: Stencil Design

- **1.** A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- **2.** The stencil thickness should be 0.125 mm (5 mils).
- **3.** The ratio of stencil aperture to land pad size should be 1:1 for the perimeter pads.

4. A 2x2 array of 1.10 x 1.10 mm openings on 1.30 mm pitch should be used for the center ground pad.

Notes: Card Assembly

- **1.** A No-Clean, Type-3 solder paste is recommended.
- **2.** The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

DOCUMENT CHANGE LIST

Revision 0.1 to Revision 0.2

- Reformatted all registers.
- Updated "9. Reference Design".
- Added "13. Pin Descriptions: Si4432" on page 155.
- Added "14. Ordering Information" on page 156.

Revision 0.2 to Revision 0.3

- Updated Pinout and Figures to reflect pin 6 and 11 now as No Connect.
- Updated Tables 1-7 footnotes for production testing.
- Updated "6.7. Preamble Length".
- Updated "3.6.6. Auto Frequency Control (AFC)".
- Updated "12.1. Complete Register Table and Descriptions".

Revision 0.3 to Revision 0.4

- **Updated register description.**
- Added XAL oscillator overview section.
- **Updated frequency calculation equations.**

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